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GS-12 -1953	PRODUCT SPECIFICATION	Amphenol ICC				
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0.5mm Board to b	ooard® Product Specification	Sanford Lu	03/27/2024			
		APPROVED BY				
		Tim Yao				
		CLASSIFICATION : UNRESTRIC	TED			

1.0 OBJECTIVE

This specification defines the performance, test, quality and reliability requirements of 0.5mm pitch Board to board® product Mating height 7.0mm~8.5mm.

2.0 <u>SCOPE</u>

This specification is applicable to the termination characteristics of 0.5mm pitch Board to board® family of products, which provides electrical connections between parallel mounted boards.

3.0 GENERAL

This document is composed of the following sections:

PARAGRAPH	TITLE
1.0	OBJECTIVE
2.0	SCOPE
3.0	GENERAL
4.0	APPLICABLE DOCUMENTS
4.1	Standards and Specifications
5.0	REQUIREMENTS
5.1	Qualification
5.2	Material
5.3	Finish
5.4	Design and Construction
5.5	Rating
6.0	PERFORMANCE
6.1	Performance
6.2	Test Methods
7.0	TEST SEQUENCE

4.0 APPLICABLE DOCUMENTS

4.1 Standards and Specifications

EIA 364: Electronic connector/socket test procedures including environmental classifications.

5.0 <u>REQUIREMENTS</u>

5.1 Qualification

Connectors furnished under this specification shall be capable of meeting the qualification test requirements specified herein.

- 5.2 Material
 - 5.2.1 Housing: All housing materials shall be high temperature plastic, rated flame retardant 94V-0 in accordance with UL-94.

5.2.2 Receptacle Terminal: Copper alloy.

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5.2.3 Plug Terminal: Copper alloy.

5.2.4 Hold Down: Copper alloy.

5.3 Finish

The finish for applicable components shall be specified in product drawings with plating area, plating material and plating thickness.

5.4 The thickness of the PCB solder paste

Below data is FCI recommended dimension, For some customer's process are different (such as, PCB thickness, solder temperature, solder paste type, etc.), customer can according to the actual application environment adjust the solder paste thickness. using solder paste thickness 0.15mm Min.

5.5 Design and Construction

The connector shall be a multi-piece assembly having two rows of contacts with surface mount soldertail terminations for installation on printed wiring board.

5.6 Rating

Voltage Rating	<30V AC
Current Rating	0.5A
Temperature Rating	-40°C ~ 125°C

6.0 PERFORMANCE

Unless otherwise specified, the performance of connectors given in the attached list shall satisfy the values specified in Table 6.1. The performance test shall follow the test method and the test sequence given in Table 6.2 & 6.3 under the environmental conditions listed below. All connectors to be tested shall be free of defects such as burr, flaw, void, blister etc. which will affect the life and application of connectors.

- Temperature ----- 15°C ~ 35°C
- Humidity ----- 25% ~ 85%
- Pressure ----- 86 ~ 106KP

6.1 Performance

TABLE 6.1

	Test Item	Requirements
6.1.1	Visual Examination	Product shall meet the requirements of product drawings. Visual Examination performed under 10X magnification.

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	Parts should be free from blistering, discoloration, cracks						
		etc.					
Electric Beguiremento							
	Electric Requireme	11.5					
612	Low Level Contact	Initial 60 mΩ Maximum					
0.1.2	Resistance(LLCR)	After test 90 mΩ Maximum					
613	Dielectric Withstanding Voltage	210 VAC,1 Minutes ,No evidence of arc-cover, insulation					
01110	Diolocalio Malocaliang Foliago	breakdown or leakage current in excess of 1 mA.					
6.1.4	Insulation Resistance	500 MΩ Minimum					
6.1.5	Current Rating	Temperature rise above ambient shall not exceed 30°C with all contacts powered at 0.5A					
Mechanical Requirements							
6.1.6	Vibration	No discontinuity greater than 1 microsecond					
6.1.7	Mating Force	10165430/10165431: 1.47N Maximum per contact					
6.1.8	Un-mating Force	10165430/10165431: 0.15N Minimum per contact.					
6.1.9	Normal Force	0.25N Min. Per mated Pair					
6110	Durability	Initial 60 mΩ Maximum					
0.1.10		After test 90 mΩ Maximum					
6.1.11	Solder-ability	Solder coverage 95% Minimum					
6.1.12	Resistance to Solder Heat	No evidence of physical or mechanical damage.					
6.1.13	Contact Retention Force	0.98N Minimum per contact.					
	Environmental Req	uirements					
6111	Thermal Shock	Initial 60 mΩ Maximum					
0.1.14		After test 90 mΩ Maximum					
6115	Temperature Life	Initial 60 mΩ Maximum					
0.1.15		After test 90 mΩ Maximum					
6116	Cyclical Humidity & Temperature	Initial 60 mΩ Maximum					
0.1.10		After test 90 mΩ Maximum					
6117	Salt Spray	Initial 60 mΩ Maximum					
0.1.17	Can opidy	After test 90 mΩ Maximum					

6.2 Test Methods

TABLE 6.2

	Test Item	Test Methods
6.2.1	Visual Examination	Visually and functionally inspected. Under 10X magnification.

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6.2.2		Receptacle Connecotr				
	Low Level Contact Resistance(LLCR)	Test Board Plug Connecotr				
		Figure 1				
		EIA-364-23				
		Test current 100 mA Maximum				
		Open circuit 20 mV Maximum				
		Number of readings 100 separable contact interface				
		minimum or 3 connectors whichever is greater				
6.2.3	Dielectric Withstanding Voltage	Test voltage 210 Vrms AC Duration 1 minute Current 1 mA Max Measure between adjacent terminals of mated connectors.				
		MIL-STD-202 Method 302				
6.0.4	Inculation Desistance	Test voltage 100 V DC				
6.2.4	Insulation Resistance	Measure between adjacent terminals of mated connectors.				
		Number of readings 30 (10 readings per connector set)				
625	Current Boting	EIA-364-70 25°C				
0.2.0		All contact powered0.5A				
		EIA-364-28				
		Frequency 10-55-10 Hz				
6.2.6	Vibration	Amplitude1.5mm				
		Current 10 mA Max				
		perpendicular axes (6 hours total).				
		EIA-364-13				
627	Mating Force	Operating speed 25 mm/minute				
0.2.1		No lubrication and utilize free-floating fixture.				
		Number of connectors 5 mated pair				
		<u>EIA-304-13</u> Operating speed 25 mm/minute				
6.2.8	Un-mating Force	No lubrication and utilize free-floating fixture.				
		Number of connectors 5 mated pair				
6.2.9	Norma Force	EIA-364-04A Method A				

		Speed: 1mm/Min. Displacement: 0.075mm
6.2.10	Durability	EIA-364-09 Operating speed 25 mm/minute Number of cycles 30
6.2.11	Solder-ability	EIA-364-52 For Non- leaded: Solder temperature 230 ± 5°C. Dip duration =3 sec Criteria: 95% coverage min
6.2.12	Resistance to Solder Heat	$\begin{array}{l} \hline \textbf{EIA-364-56} \\ \hline \textbf{For Non- leaded:} \\ \hline \textbf{Peak temperature 260 \pm 5^{\circ}\text{C.} \\ \hline Duration$
6.2.13	Contact Retention Force	Operating speed 25 mm/minute
6.2.14	Thermal Shock	EIA-364-32 Method A Temperature range40 +0/-5°C to 125 +5/-0°C Time at temperature extremes 30 minutes Test Duration (A-4) 10 cycles Transfer Time 5 minutes maximum
6.2.15	Temperature Life	EIA-364-17 Subject product to 85±2°C for 96 hours
6.2.16	Cyclical Humidity & Temperature	65°c 90~98%
6.2.17	Salt Spray	EIA-364-26 5±1% salt concentration 24 hours 35±2°C

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7.0 QUALIFICATION TEST MATRIX

TESTITEM					TES	T GR	OUP									
	Section	1	2	3	4	5	6	7	8	9	10					
Visual Examination	6.2.1	1,9	1,5	1,3	1,3	1,3	1,7	1,5	1,10	1,5	1,3					
Low Level Contact Resistance (LLCR)	6.2.2	2,8	2,4				2,4,6	2,4		2,4						
Dielectric Withstanding Voltage	6.2.3								3,6,9							
Insulation Resistance	6.2.4								2,5,8							
Current Rating	6.2.5										2					
Vibration	6.2.6		3													
Mating Force	6.2.7	3,6														
Un-mating Force	6.2.8	4,7														
Normal Force	6.2.9															
Durability	6.2.10	5														
Solder-ability	6.2.11			2												
Resistance To Solder Heat	6.2.12				2											
Contact Retention Force	6.2.13					2										
Thermal Shock	6.2.14						3		4							
Temperature Life	6.2.15							3								
Cyclical Humidity & Temperature	6.2.16						5		7							
Salty Spray	6.2.17									3						
Number of Samples		5	3	3	3	3	3	3	3	5	3					

8.0 RECORD RETENTION

REV	PAGES	DESCRIPTION	EC #	DATE
A	ALL	NEW RELEAS	-	27 Mar '24